

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Naoki KAWANABE, et al.
Application No.: Not Yet Assigned
Filed: On even date herewith
For: A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE TO PROVIDE IMPROVED ADHESION BETWEEN BONDING PADS AND BALL PORTIONS OF ELECTRICAL CONNECTORS (As Amended)
Art Unit: Not Yet Assigned
Examiner: Not Yet Assigned

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 24, 2004

Sir:

Prior to examination, please amend the above-identified application as listed below and as set forth on the following pages:

Amendments to the Title;

Amendments to the Abstract;

Amendments to the Claims;

Remarks are included following the amendments; and

Appendix A including the new Abstract is attached following the remarks.